

GRAPHICS LCD MODULE SPECIFICATIONS



| Crystalfontz Model Number | CFAX12864U1-TFH |
|---------------------------|---|
| | |
| Product Pages | http://www.crystalfontz.com/product/CFAX12864U1TFH.html |

Crystalfontz America, Incorporated 12412 East Saltese Avenue Spokane Valley, WA 99216-0357 Phone: 888-206-9720 Fax: 509-892-1203 Email: techinfo@crystalfontz.com URL: www.crystalfontz.com

REVISION HISTORY

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| HA | KU | WA | KE |

| HARDWARE | | | | |
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| | DATA SHEET |
|------------|--|
| 2010/12/06 | Current Data Sheet In Section 11. Backlight Information, corrected specifications for Supply Voltage and Reverse Voltage. Specifications were reversed. |
| 2009/02/24 | Data Sheet version: Preliminary New Data Sheet. |

The Fine Print

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1. Module Classification Information

$\begin{array}{c|c} \underline{CFA} \underbrace{X} \\ \hline 0 \\ \hline \end{array} & \begin{array}{c} \underline{1} & \underline{2} & \underline{8} & \underline{6} & \underline{4} \\ \hline 3 \\ \hline \end{array} & \begin{array}{c} \underline{U1} \\ \hline \\ \hline \end{array} & \begin{array}{c} \underline{T} & \underline{F} & \underline{H} \\ \hline \\ \hline \\ \hline \\ \hline \end{array} & \begin{array}{c} \underline{S} & \underline{6} \\ \hline \end{array} & \begin{array}{c} \overline{O} \\ \hline \end{array} & \begin{array}{c} \underline{CFA} \\ \hline \end{array} & \begin{array}{c} \underline{X} \\ \underline{C} \\ \hline \end{array} & \begin{array}{c} \underline{CFA} \\ \underline{S} \\ \underline{C} \\ \hline \end{array} & \begin{array}{c} \underline{CFA} \\ \underline{S} \\ \underline{C} \\ \hline \end{array} & \begin{array}{c} \underline{CFA} \\ \underline{C} \\ \underline{C} \\ \underline{C} \\ \hline \end{array} & \begin{array}{c} \underline{CFA} \\ \underline{C} \\ \underline$

| 1 | Brand : CRYSTALF | ONTZ AMERICA, INCORPOR | RATED | | | | |
|---|---|--|--|--|--|--|--|
| 2 | Display Type : $H \rightarrow$ Character Type, $G \rightarrow$ Graphic Type, $X \rightarrow TAB$ Type | | | | | | |
| 3 | Display's logical dimensions: 128 pixels by 64 pixels | | | | | | |
| 4 | Model variant: U (1→ | module with ZIF tail) | | | | | |
| 5 | Backlight Type: | $N \rightarrow Without backlight$ | P→LED, Bule | | | | |
| | | B→EL, Blue green | A→LED, Amber | | | | |
| | | D→EL, Green | R→LED, Red | | | | |
| | | $W \rightarrow EL$, White | O→LED, Orange | | | | |
| | | $F \rightarrow CCFL$, White | G→LED, Green | | | | |
| | | Y→LED, Yellow Green | $T \rightarrow LED$, White | | | | |
| 6 | LCD Mode: | B→TN Positive, Gray | T→FSTN Negative | | | | |
| | | N→TN Negative, | | | | | |
| | | G→STN Positive, Gray | | | | | |
| | | $Y \rightarrow STN$ Positive, Yellow Green | | | | | |
| | | M→STN Negative, Blue | | | | | |
| | | F→FSTN Positive | | | | | |
| Ø | LCD Polarizer Type/ | A→Reflective, N.T, 6:00 | H→Transflective, W.T,6:00 | | | | |
| | Temperature range/ View direction | D→Reflective, N.T, 12:00 | $K \rightarrow$ Transflective, W.T,12:00 | | | | |
| | view direction | G→Reflective, W. T, 6:00 | $C \rightarrow$ Transmissive, N.T,6:00 | | | | |
| | | J→Reflective, W. T, 12:00 | $F \rightarrow$ Transmissive, N.T, 12:00 | | | | |
| | | B→Transflective, N.T,6:00 | I→Transmissive, W. T, 6:00 | | | | |
| | | $E \rightarrow$ Transflective, N.T.12:00 | L→Transmissive, W.T,12:00 | | | | |
| 8 | Special Code | CB: | | | | | |

2. Precautions in use of LCD Modules

- (1) Avoid applying excessive shocks to the module or making any alterations or modifications to it.
- (2) Don't make extra holes on the printed circuit board, modify its shape or change the components of LCD module.
- (3) Don't disassemble the LCM.
- (4) Don't operate it above the absolute maximum rating.
- (5) Don't drop, bend or twist LCM.
- (6) Soldering: only to the I/O terminals.
- (7) Storage: please storage in anti-static electricity container and clean environment.

3.General Specification

| Item | Dimension | Unit |
|----------------------|------------------------------|------|
| Number of Characters | 128 x 64 | - |
| Module dimension | 56.0 x 42.5 x 1.9(MAX) | mm |
| View area | 52.0x 33.5 | mm |
| Active area | 47.34x 30.29 | mm |
| Dot size | 0.35 x 0.4 | mm |
| Dot pitch | 0.37 x 0.42 | mm |
| LCD type | FSTN Positive, Transflective | |
| Duty | 1/64 | |
| View direction | 6 o'clock | |
| Backlight Type | LED white | |

4. Absolute Maximum Ratings

| Item | Symbol | Min | Тур | Max | Unit |
|--------------------------|----------------------|-----------------|-----|-----------------|------|
| Operating Temperature | T _{OP} | -20 | _ | +70 | °C |
| Storage Temperature | T _{ST} | -30 | _ | +80 | °C |
| Input Voltage | VI | V _{SS} | _ | V _{DD} | V |
| Supply Voltage For Logic | VDD-V _{SS} | 1.8 | _ | 3.6 | V |
| Supply Voltage For LCD | Vout-V _{SS} | 6.0 | | 14.2 | V |

5. Electrical Characteristics

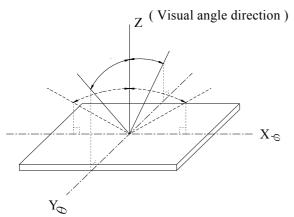
| Item | Symbol | Condition | Min | Тур | Max | Unit |
|-----------------------------|----------------------|-----------------------|---------------------|------|---------------------|------|
| Supply Voltage For Logic | V_{DD} - V_{SS} | — | 3.0 | 3.3 | 3.6 | V |
| | | Ta=-20°C | _ | _ | _ | V |
| Supply Voltage For LCD | V_{DD} - V_{0UT} | Ta=25°C | _ | 8.5 | _ | V |
| | | Ta=70°C | _ | | _ | V |
| Input High Volt. | V_{IH} | _ | 0.8 V _{DD} | _ | V _{DD} | V |
| Input Low Volt. | V _{IL} | _ | Vss | _ | 0.2 V _{DD} | V |
| Output High Volt. | V _{OH} | _ | 0.8 V _{DD} | _ | V _{DD} | V |
| Output Low Volt. | V _{OL} | _ | Vss | _ | 0.2 V _{DD} | V |
| Supply Current | I _{DD} | V _{DD} =3.3V | 0.18 | 0.18 | 0.18 | mA |

6. Optical Characteristics

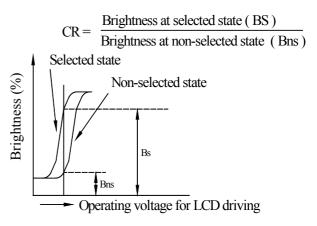
| Item | Symbol | Condition | Min | Тур | Max | Unit |
|----------------|---------------|------------|-----|-----|-----|------|
| | $(V) \theta$ | $CR \ge 2$ | 30 | — | 60 | deg |
| View Angle | (H) φ | $CR \ge 2$ | -45 | _ | 45 | deg |
| Contrast Ratio | CR | _ | _ | 5 | | _ |
| | T rise | _ | _ | 110 | 220 | ms |
| Response Time | T fall | _ | _ | 260 | 520 | ms |

6.1 Definitions

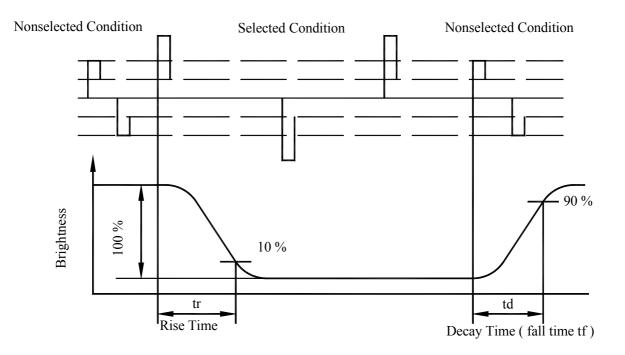
View Angles



Contrast Ratio



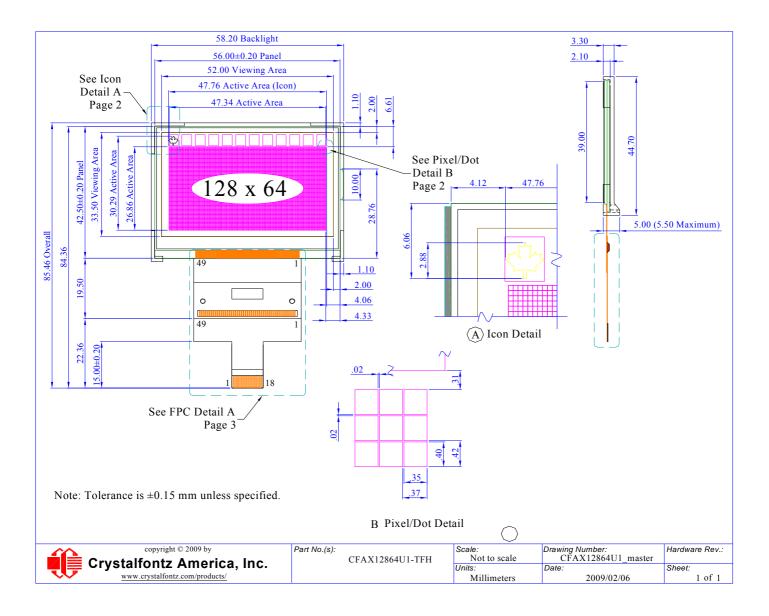
Response Time



7.Interface Description

| Pin No. | Symbol | I/O | Description | | | | | | |
|---------|---------|-----|-------------------------------------|--|----------------|---------------------|--------------------|--------|--|
| 1 | VDD | | Power supply pin for logic. | | | | | | |
| 2 | VSS | | | Ground pin, connected to 0V | | | | | |
| 3 | CS1B | 1 | Chip se | elect input pins | | | | | |
| | | | | struction i/o is enable | ed only wher | n CS1Bis"L"an | d CS2"H". | | |
| | | | When c | hip select is non-acti | ve,DB0 TO | DB7 may be hi | gh impedance. | | |
| 4 | CS2 | 1 | | elect input pins | , | 2 | 0 1 | | |
| | | | - | Data/instruction i/o is enabled only when CS1Bis"L"and CS2"H". | | | | | |
| | | | When c | hip select is non-acti | ve,DB0 TO | DB7 may be hi | gh impedance. | | |
| 5 | RES | I | Reset in | Reset input pin | | | | | |
| | | | | RESETB is "L", initi | | | | | |
| | | | This is | connected to the leas | st significant | bit of the norm | al MPU address | bus, | |
| 6 | A0 | | | etermines whether th | | | nmand. | | |
| 0 | AU | Ι | | A0="H": Indicate that D0 to D7 are display data | | | | | |
| | | | | ": Indicate that D0 to | | rol data | | | |
| 7 | R/W | I | | connected to 80-fami | • | | | | |
| | | | | nable clock input pir | . The data O | N DB0~DB7 a | re latched at the | rising | |
| | | | • | edge of the /WR signal. | | | | | |
| | | | | connected to 68-fami | ly MPU: | | | | |
| | | | | 'H'': read | | | | | |
| 0 | E | | | L": write | | | | | |
| 8 | E | I | | connected to 80-fami | • | | D7 are in an outr | | |
| | | | status | hable clock input pin | . when /RD | IS L, DB0~D | B / are in an outp | but | |
| | | | | connected to 68-fami | | | | | |
| | | | | "H": When E is "H", | | re in an output | status | | |
| | | | | "L": The data on DB(| | - | | F | |
| | | | signal | | | tened at the fai | ling edge of the l | | |
| 9-16 | DB0-DB7 | I/O | 0 | -directional data bus | that is conne | ected to the star | dard 8-bit | | |
| 0 10 | | | | rocessor data bus. | | | | | |
| | | | - | he serial interface se | lected(PS="I | _") | | | |
| | | | | B5: high impedance | | , | | | |
| | | | | erial input clock (SC | | | | | |
| | | | | erial input data (SID) | | | | | |
| | | | When c | chip select is not activ | ve, DB0~DB | 7 may be high | impedance. | | |
| | | | | the MPU interface sy | | al | | | |
| 17 | C86 | Ι | | 'H":6800 Series MP | | | | | |
| | | | C86 = "L":8080 Series MPU interface | | | | | | |
| | | | | the parallel data inpu | | input switch ter | rminal | | |
| | | | | H":Parallel data inpu | it | | | | |
| | | | | L":Serial data input | 1. (1 | | | | |
| | | | I ne toi | lowing applies deper | aing on the | P/S status: | i | | |
| | | | P/S | Data/Command | Data | Read/Write | Serial Clock | | |
| 18 | P/S | Ι | "H" | 4.0 | | | | | |
| | | | н | A0 | D0 to D7 | /RD, /WR | - | | |
| | | | "L" | A0 | SI (D7) | Write only | SCL (D6) | | |
| | | | When I | D/Q = "I" fix D0 D5 | node to VDI | + O or VSS lovel | /DD(E) and /W/ |)) | |
| | | | | $P/S = "L", fix D0 \sim D5$ | | | | | |
| | | | | are fixed to either "H | UIL.WI | ii serai uata inp | ui, raivi display | uala | |
| | | | reading is not supported. | | | | | | |

8. Contour Drawing & Block Diagram



9. Fuction Description

Refer to IC NT7534 data sheet

10.<u>RELIABILITY</u>

Content of Reliability Test (wide temperature, -20°c~70°C)

| | Environmental Test | | |
|---|---|---|------|
| Test Item | Content of Test | Test Condition | Note |
| High Temperature storage | Endurance test applying the high storage temperature for a long time. | 80°C 200hrs | 2 |
| Low Temperature storage | Endurance test applying the high storage temperature for a long time. | -30°C 200hrs | 1,2 |
| High Temperature Operation | Endurance test applying the electric stress (Voltage & Current) and the thermal stress to the element for a long time. | 70℃ 200hrs | |
| Low Temperature Operation | Endurance test applying the electric stress under low temperature for a long time. | -20°C 200hrs | 1 |
| High Temperature/ Humidity Operation | The module should be allowed to stand at 60 °C,90%RH max For 96hrs under no-load condition excluding the polarizer, Then taking it out and drying it at normal temperature. | 60℃,90%RH 96hrs | 1,2 |
| Thermal shock resistance | The sample should be allowed stand the following 10 cycles of operation $-20^{\circ}C$ $25^{\circ}C$ $70^{\circ}C$ 30min 5min 30min 1 cycle | -20°C /70°C 10 cycles | |
| Vibration test | Endurance test applying the vibration during transportation and using. | Total fixed amplitude : 15mm Vibration Frequency : 10~55Hz One cycle 60 seconds to 3 directions of X,Y,Z for Each 15 minutes | 3 |
| Static electricity test | Endurance test applying the electric stress to the terminal. | VS=800V,RS=1.5kΩ CS=100pF 1 time | |

Note1: No dew condensation to be observed.

Note2: The function test shall be conducted after 4 hours storage at the normal

Temperature and humidity after remove from the test chamber.

Note3: Vibration test will be conducted to the product itself without putting it in a container.

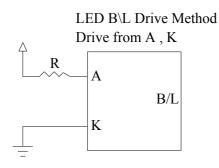
11.Backlight Information

| SYMBOL | MIN | ТҮР | MAX | UNIT | TEST CONDITION |
|--------|-----------------|---------|------------------------------------|---|--|
| ILED | 43.2 | 48 | 75 | mA | V=3.5V |
| V | | | 5 | V | _ |
| VR | | 3.4 | 3.5 | 3.6 | V – |
| IV | 120 | 150 | | CD/M ² | ILED=48mA |
| _ | _ | 10K | _ | Hr. | ILED=48mA 25°C,50-60%RH, (Note 1) |
| | ILED V VR | V VR | ILED 43.2 48 V | ILED 43.2 48 75 V 5 5 VR 3.4 3.5 IV 120 150 | ILED 43.2 48 75 mA V 5 V VR 3.4 3.5 3.6 IV 120 150 CD/M ² |

Note: The LED of B/L is drive by current only, drive voltage is for reference only.

drive voltage can make driving current under safety area (current between minimum and maximum).

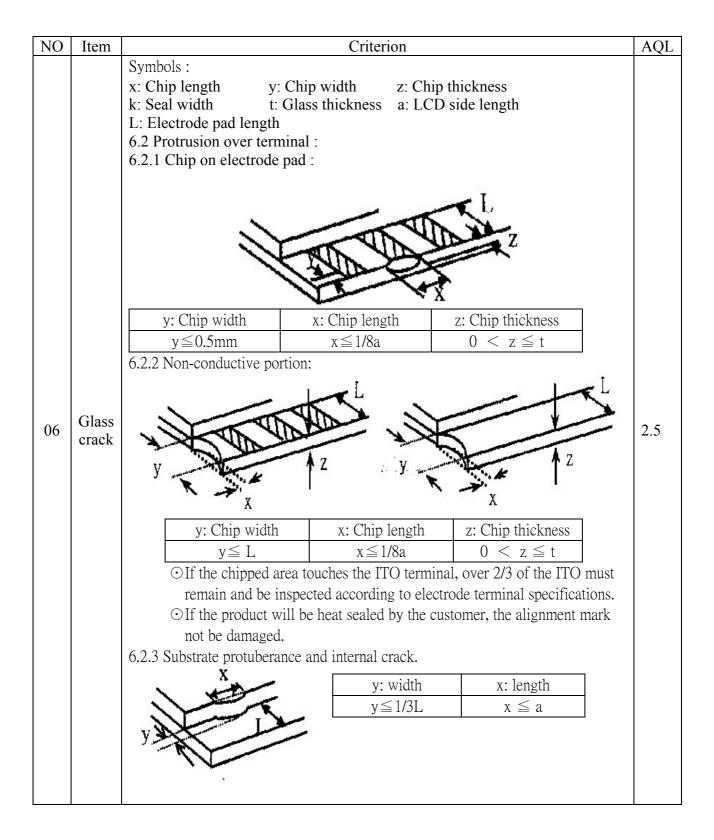
Note1 : 10K hours is only an estimate for reference.



12. Inspection specification

| NO | Item | | Criterion | | AQL |
|----|---|--|---|---|------|
| 01 | Electrical Testing | 1.1 Missing vertical, horizontal segment, segment contrast defect. 1.2 Missing character , dot or icon. 1.3 Display malfunction. 1.4 No function or no display. 1.5 Current consumption exceeds product specifications. 1.6 LCD viewing angle defect. 1.7 Mixed product types. 1.8 Contrast defect. | | | 0.65 |
| 02 | Black or white spots on LCD (display only) | 2.1 White and black spots on display ≤0.25mm, no more than three white or black spots present. 2.2 Densely spaced: No more than two spots or lines within 3mm | | | 2.5 |
| 03 | LCD black spots, white spots, contamination (non-display) | 3.1 Round type : As $\Phi = (x + y) / 2$ A | following drawing $SIZE$ $\Phi \leq 0$ $0.10 < \Phi \leq 0$ $0.20 < \Phi \leq 0$ $0.25 < \Phi$ | 0.20 2 | 2.5 |
| | | | ollowing drawing) ength Width $W \le 0.02$ ≤ 3.0 $0.02 < W \le 0.02$ ≤ 2.5 $0.03 < W \le 0.02$ $0.05 < W$ | /) | 2.5 |
| 04 | Polarizer bubbles | If bubbles are visible, judge using black spot specifications, not easy to find, must check in specify direction. | Size Φ $\Phi \leq 0.20$ $0.20 < \Phi \leq 0.50$ $0.50 < \Phi \leq 1.00$ $1.00 < \Phi$ Total Q TY | Acceptable Q TY Accept no dense 3 2 0 3 3 | 2.5 |

| Item | Criterion | | | AQL |
|-----------|---|---|---|---|
| Scratches | Follow NO.3 LCD black spots, white spots, contamination | | | |
| | Symbols Define: x: Chip length y: Chip width z: Chip thickness k: Seal width t: Glass thickness a: LCD side length L: Electrode pad length: 6.1 General glass chip : 6.1.1 Chip on panel surface and crack between panels: | | | |
| | z: Chip thickness | y: Chip width | x: Chip length | |
| | Z≦1/2t | Not over viewing area | x≦1/8a | |
| glass | $1/2t < z \leq 2t$ | Not exceed 1/3k | x≦1/8a | 2.5 |
| | 6.1.2 Corner crack: | y: Chip width Not over viewing area Not exceed 1/3k | $x: Chip length$ $x \le 1/8a$ $x \le 1/8a$ | |
| | Scratches | ScratchesFollow NO.3 LCD blackSymbols Define: x: Chip length k: Seal width t L: Electrode pad length 6.1 General glass chip 6.1.1 Chip on panel sum $6.1.1$ Chip on panel sum 1.1 Chip on panel sum $z \le 1/2t$ $1/2t < z \le 2t$ \odot If there are 2 or more $6.1.2$ Corner crack: $z:$ Chip thickness $Z \le 1/2t$ $1/2t < z \le 2t$ $chip thickness$ $Z \le 1/2t$ $z \le 1/2t$ $1/2t < z \le 2t$ | ScratchesFollow NO.3 LCD black spots, white spots, contSymbols Define: x: Chip length k: Seal width t: Glass thickness t: Glass thickness a: LCE L: Electrode pad length:6.1 General glass chip : 6.1.1 Chip on panel surface and crack between pChipped glassZ: Chip thickness glassy: Chip width Z $\leq 1/2t$ Not over viewing area 1/2t < z $\leq 2t$ Not exceed 1/3k \odot \odot If there are 2 or more chips, x is total length of e 6.1.2 Corner crack: $z: Chip thicknessy: Chip widthZ \leq 1/2tZ: Chip thicknessy: Chip widthZ \leq 1/2tX: Chip thicknessy: Chip widthZ \leq 1/2t$ | ScratchesFollow NO.3 LCD black spots, white spots, contaminationSymbols Define: x: Chip length L: Electrode pad length:Symbols Define: x: Chip width t: Glass thickness a: LCD side length L: Electrode pad length:6.1 General glass chip : 6.1.1 Chip on panel surface and crack between panels:6.1 General glass chip : 6.1.1 Chip on panel surface and crack between panels:Chipped glassZ: Chip thickness Z $\leq 1/2t$ Not over viewing areax $\leq 1/8a$ 1/2tNot exceed 1/3kx $\leq 1/8a$ Off there are 2 or more chips, x is total length of each chip.6.1.2 Corner crack:Image: Chip width x: Chip length Z $\leq 1/2t$ Not exceed 1/3kx $\leq 1/8a$ Off there are 2 or more chips, x is total length of each chip.6.1.2 Corner crack:Image: Chip width x: Chip length Z $\leq 1/2t$ Not over viewing areax $\leq 1/8a$ |



| NO | Item | Criterion | |
|--------------|-----------------------|--|---|
| 07 | Cracked glass | The LCD with extensive crack is not acceptable. | |
| 08 | Backlight elements | 8.1 Illumination source flickers when lit. 8.2 Spots or scratched that appear when lit must be judged. Using LCD spot, lines and contamination standards. 8.3 Backlight doesn' t light or color wrong. | |
| 09 | Bezel | 9.1 Bezel may not have rust, be deformed or have fingerprints, stains or other contamination.9.2 Bezel must comply with job specifications. | |
| 10 PCB \ COB | | 10.1 COB seal may not have pinholes larger than 0.2mm or contamination. 10.2 COB seal surface may not have pinholes through to the IC. 10.3 The height of the COB should not exceed the height indicated in the assembly diagram. 10.4 There may not be more than 2mm of sealant outside the seal area on the PCB. And there should be no more than three places. 10.5 No oxidation or contamination PCB terminals. 10.6 Parts on PCB must be the same as on the production characteristic chart. There should be no wrong parts, missing parts or excess parts. 10.7 The jumper on the PCB should conform to the product characteristic chart. 10.8 If solder gets on bezel tab pads, LED pad, zebra pad or screw hold pad, make sure it is smoothed down. 10.9 The Scraping testing standard for Copper Coating of PCB | 2.5 2.5 0.65 2.5 2.5 0.65 0.65 2.5 2.5 2.5 |
| 11 | Soldering | 11.1 No un-melted solder paste may be present on the PCB. 11.2 No cold solder joints, missing solder connections, oxidation or icicle. 11.3 No residue or solder balls on PCB. 11.4 No short circuits in components on PCB. | 2.5 2.5 2.5 0.65 |

| NO | Item | Criterion | AQL |
|----|-----------------------|---|--|
| 12 | General appearance | 12.1 No oxidation, contamination, curves or, bends on interface Pin (OLB) of TCP. 12.2 No cracks on interface pin (OLB) of TCP. 12.3 No contamination, solder residue or solder balls on product. 12.4 The IC on the TCP may not be damaged, circuits. 12.5 The uppermost edge of the protective strip on the interface pin must be present or look as if it causes the interface pin to sever. 12.6 The residual rosin or tin oil of soldering (component or chip component) is not burned into brown or black color. 12.7 Sealant on top of the ITO circuit has not hardened. 12.8 Pin type must match type in specification sheet. 12.9 LCD pin loose or missing pins. 12.10 Product packaging must the same as specified on packaging specification sheet. 12.11 Product dimension and structure must conform to product specification sheet. | 2.5 0.65 2.5 2.5 2.5 2.5 2.5 0.65 0.65 0.65 0.65 |